

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Gabric, *et al.* Docket No.: INF 2006 VJ 33543 US  
Serial No.: 10/586,788 Art Unit: TBD  
Filed: July 21, 2006 Examiner: TBD  
I.A. Filing Date: January 22, 2005 I.A. No.: PCT/DE2005/000088  
For: Plasma Excited Chemical Vapor Deposition Method,  
Silicon/Oxygen/Nitrogen-Containing-Material and Layered Assembly

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

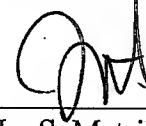
**Transmittal of English Translation of Specification**

Dear Sir:

Attached is an English translation of the above-identified specification, which was filed in German as PCT/DE2005/000088. I hereby attest that this translation is a true and accurate translation of the PCT application as published.

Respectfully submitted,

9/2/08  
Date

  
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